



# HITHERM<sup>™</sup> Thermal Interface Materials

**TECHNICAL DATA SHEET 318** 

#### **Product Overview**

eGRAF<sup>®</sup> HITHERM<sup>™</sup> thermal interface materials are designed for use in applications requiring low contact resistance and high thermal conductivity. The flexible graphite materials can be die-cut and/or laminated with plastics and adhesives.

#### **Part Designation**

Every eGRAF<sup>®</sup> HITHERM<sup>™</sup> thermal interface part number defines the grade and coating options of the material and is constructed based on the following example:

## **Product Series Characteristics**<sup>[1]</sup>

CHARACTERISTIC	UNIT	<b>PURE GRAPHITE</b>	POLYMER ENHANCED
CHARACTERISTIC	UNIT	HT-1200 Series	HT-2500 Series
Thermal Impedance @ 200 kPa	K cm <sup>2</sup> /W	HT-1205 = 0.59	HT-2505 = 0.41
	K-cm <sup>2</sup> /W	HT-1210 = 0.66	HT-2510 = 0.58
Thermal Impedance @ 700 kPa	K-cm²/W	HT-1205 = 0.30	HT-2505 = 0.24
mermat impedance @ 700 kFa		HT-1210 = 0.40	HT-2510 = 0.41
Typical Thermal Conductivity <sup>[2]</sup> @ 700 kPa Through-Plane • In-Plane	W/m-K	10•150	16•120
Typical Thickness with Tolerance			
0.127 mm (0.005") ± 10%	-	HT-1205	HT-2505
0.25 mm (0.010") ± 5%		HT-1210	HT-2510
0.51 mm (0.020") ± 5%		HT-1220	-
Electrical Resistivity <sup>[3]</sup>	μΩm	60•1230	80•1550
In-Plane • Through Thickness	μ	00 1200	00 1000
Hardness (Shore A)		85	
Coefficient of Thermal Expansion (CTE) In Plane • Through-Plane	ppm/°C	-0.4 • 27.0	
Flammability Rating	UL	94V-0	
Operating Temperature	°C	-40 to +400	-25 to +125
Specific Heat @ 25°C	J/g-°C	0.71	
RoHS Compliant	-	Yes	
Lead / Halogen Free	-		Yes

THERMAL INTERFACE MATERIAL			OPTIONAL COATING	
HT	—	12	10	Α
Product Name		Series Name	Typical Graphite Thickness (thousands of an inch)	Adhesive

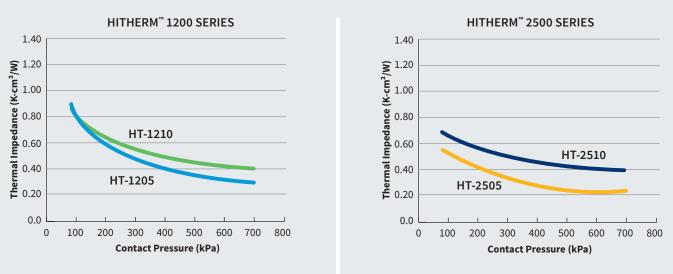
# eGRAF<sup>®</sup> HITHERM™ THERMAL INTERFACE MATERIALS

### HITHERM<sup>™</sup> Thermal Interface Materials - Adhesive Coating Option

CHARACTERISTIC	ADHESIVE "A" COATING*		
Nominal Thickness (mm • inches)	0.008 • 0.0003		
Operating Temperature (°C)	-40 to +150		
Thermal Impedance <sup>[4]</sup> per Side (cm² °C/W @ 110 kPa)	0.16		
Thermal Conductivity (W/m-K)	-		
Dielectric Strength (V) -			
Adhesive Strength <sup>[5]</sup> (g/cm <sup>2</sup> )	700 Typical 450 Minimum		

\*Adhesive not available on HT-1220 Grade

#### **Thermal Impedance vs. Interface Pressure**



Notes:

[1] Properties listed are typical and cannot be used as accept/reject specifications.

[2] In-Plane conductivity at ambient temperature determined using Angstrom's Method. Through-plane conductivity determined using ASTM D5470 Modified Method.

[3] ASTM C611.4 Point Resistivity Test.

[4] ASTM D5470 Modified (at 110kPa/16 psi/1.1 bar). Total thermal impedance = thermal impedance of graphite + thermal impedance of coating. [5] Adhesive Strength is based on a lap shear test (ASTM D3163) with material adhering to a glass plate.

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